

<b>Notice of References Cited</b>	Application/Control No. 10/024,957	Applicant(s)/Patent Under Reexamination MALUF ET AL.	
	Examiner Robert A. Siconolfi	Art Unit 3683	Page 1 of 1

**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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	B	US-5,909,078	06-1999	Wood et al.	310/307
	C	US-6,019,437	02-2000	Barron et al.	303/113.1
	D	US-			
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	K	US-			
	L	US-			
	M	US-			

**FOREIGN PATENT DOCUMENTS**

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	N					
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**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Klaassen et al, "Silicon Fusion Bonding and DeepReactive Ion Etching; A New Technology For Microstructures" Proc.Transducers 95 Stockholm Sweden pp.556-559
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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.